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(54) Title: LIQUID COOLING APPARATUS FOR ENCAPSULATED COOLING OF ONBOARD HIGH-HEAT GENERATING ELECTRONIC COMPONENTS

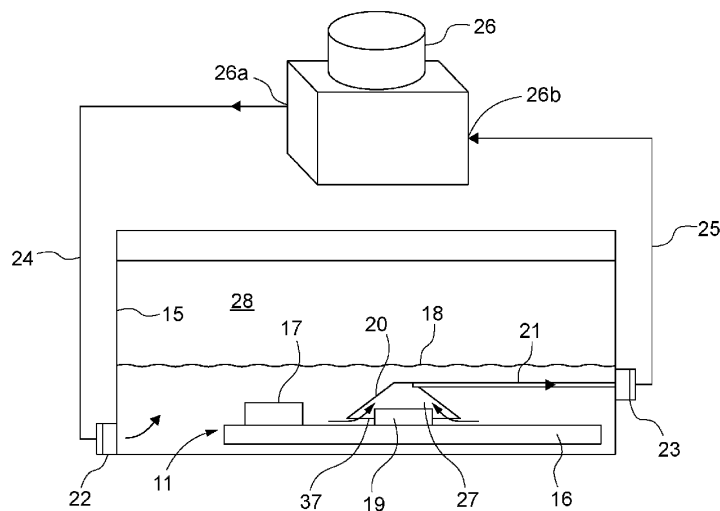


Fig. 3

(57) Abstract: A liquid cooling apparatus and system for the immersion cooling of electronic devices including in particular servers and other IT hardware nodes having an array of heat generating devices including microprocessors, RAM, motherboards etc having different operational temperatures. The present apparatus and system is adapted for the partitioned liquid cooling of a plurality of heat generating electronic components with at least some of the components being segregated spatially relative to other electronic components for separate cooling by the dielectric liquid. The multi-stage segregated heat transfer to the coolant fluid provides enhanced energy efficiency and operational performance of the electronic devices.

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